

To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HSS104

Silicon Epitaxial Planar Diode for High Speed Switching

RENESAS

ADE-208-178B (Z)

Rev.2
Oct. 2000

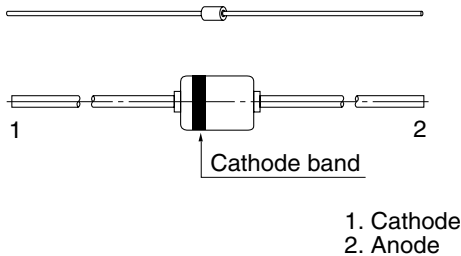
Features

- Short reverse recovery time and forward recovery time.
- Suitable for 5 mm pitch high speed automatically insertion.
- Small glass package (MHD) enables easy mounting and high reliability.

Ordering Information

Type No.	Cathode band	Package Code
HSS104	Blue	MHD

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	V_{RM}	40	V
Reverse voltage	V_R	35	V
Average rectified current	I_O	110	mA
Peak forward current	I_{FM}	300	mA
Non-Repetitive peak forward surge current	I_{FSM}^*	0.4	A
Power dissipation	Pd	300	mW
Junction temperature	Tj	175	°C
Storage temperature	Tstg	-65 to +175	°C

Note: Within 1s forward surge current.

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_F	—	—	1.2	V	$I_F = 100 \text{ mA}$
Reverse current	I_R	—	—	0.5	μA	$V_R = 35 \text{ V}$
Capacitance	C	—	—	3.0	pF	$V_R = 0.5 \text{ V}, f = 1 \text{ MHz}$
Reverse recovery time	t_{rr}	—	—	3.0	ns	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}, R_L = 50 \Omega$

Main Characteristic

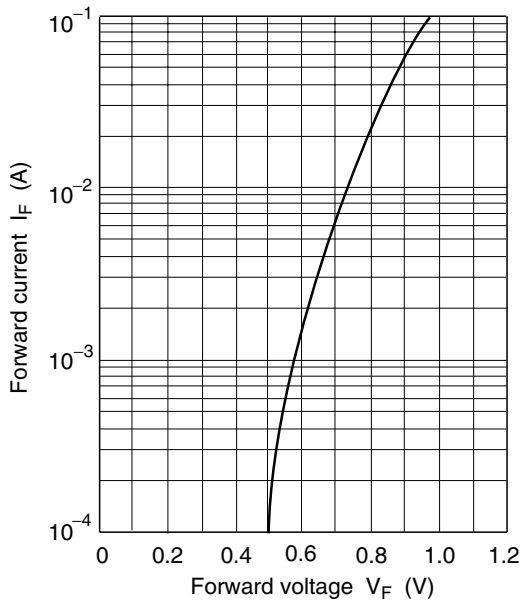


Fig.1 Forward current Vs. Forward voltage

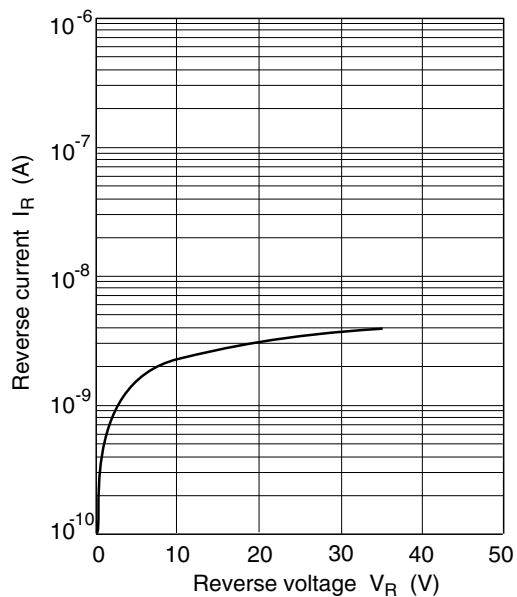


Fig.2 Reverse current Vs. Reverse voltage

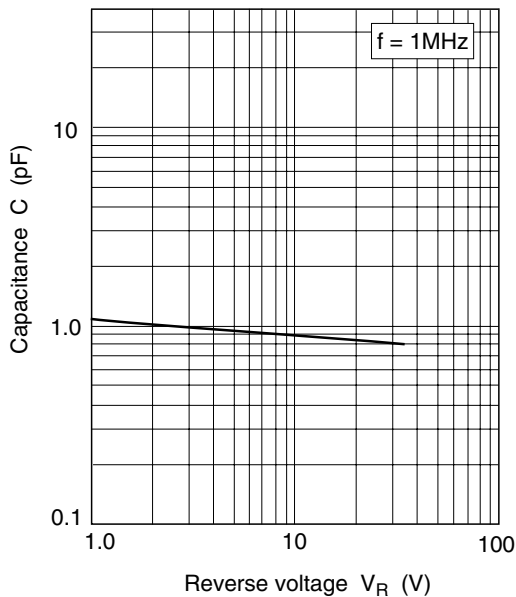
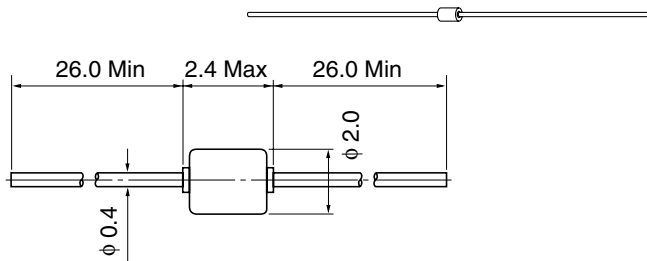


Fig.3 Capacitance Vs. Reverse voltage

Package Dimensions

Unit: mm



Hitachi Code	MHD
JEDEC	Conforms
EIAJ	—
Mass (reference value)	0.084 g

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